

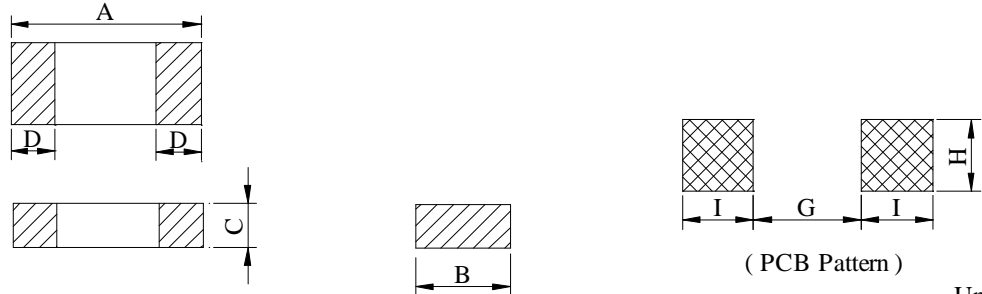
SPECIFICATION FOR APPROVAL

REF :

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	M□□□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

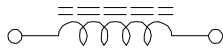
I . CONFIGURATION & DIMENSIONS :



Unit : m/m

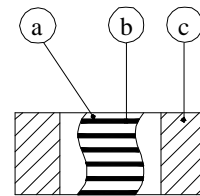
Series	A	B	C	D	G	H	I
M□1608	1.6±0.2	0.8±0.2	0.8±0.2	0.30±0.2	0.7	0.7	0.7
M□2029	2.0±0.2	1.2±0.2	0.9±0.2	0.50±0.3	1.0	1.0	1.0
M□3261	3.2±0.2	1.6±0.2	1.1±0.2	0.60±0.4	2.2	1.4	1.1

II . SCHEMATIC DIAGRAM :



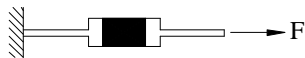
III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



IV . GENERAL SPECIFICATION :

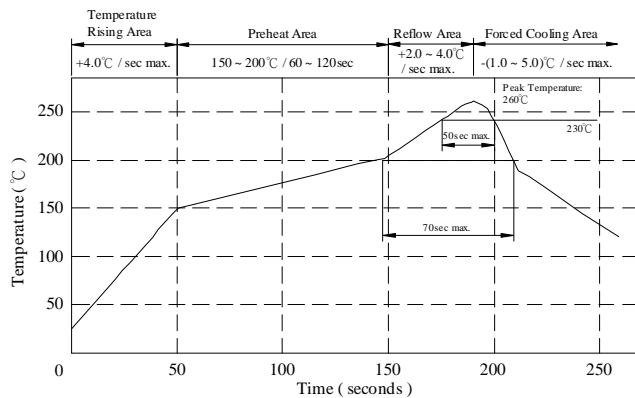
- a . Storage temp. : -40 ---- +105°C
- b . Operating temp. : -55 ---- +125°C
- c . Terminal strength :



Type	F (kgf)	Time (sec)
M□1608	0.5	
M□2029	0.6	30±5
M□3261	1.0	

- d . Solderability : Preheat : 150±25°C for 60 seconds
 Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
 Solder temp. : 260±5°C
 Flux : Rosin
 Dip time : 4±1 seconds

Peak Temp : 260°C max.
 Max time above 230°C : 50sec max.
 Max time above 200°C : 70sec max.



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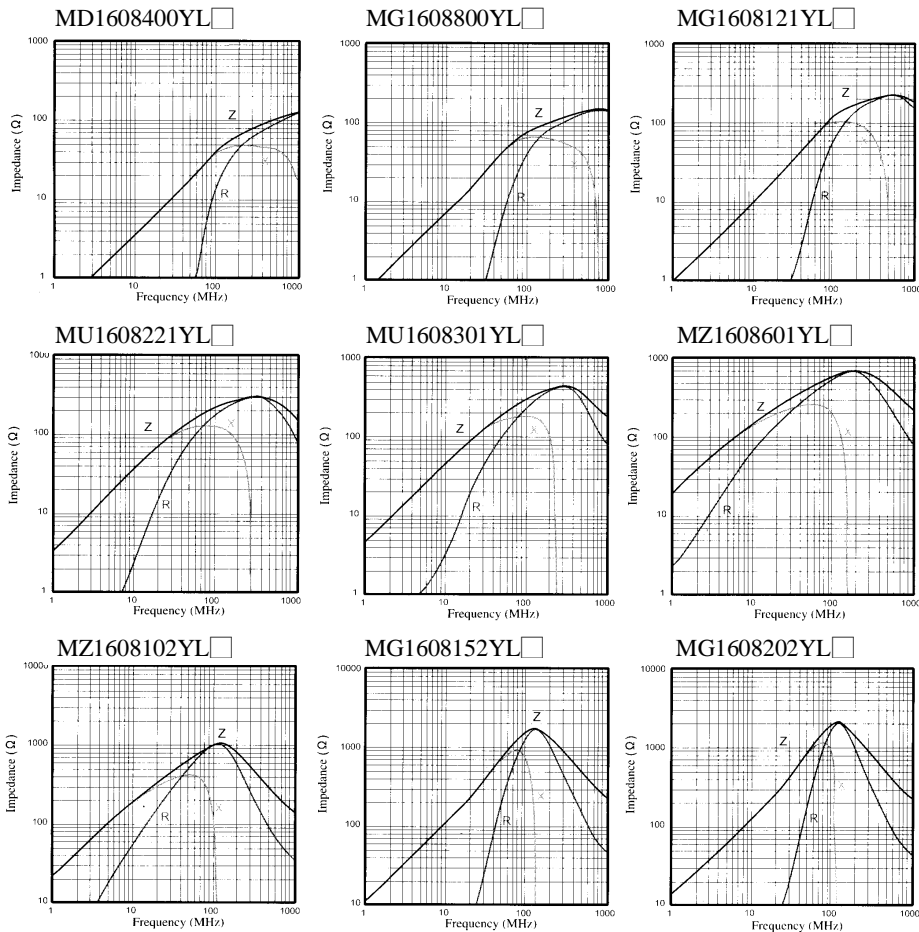
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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	M□□□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω) at 100MHz	RDC (Ω) max.	IDC (mA) max.
MD1608400YL□-□□□	40±25%	0.30	300
MG1608800YL□-□□□	80±25%	0.30	300
MG1608121YL□-□□□	120±25%	0.30	200
MU1608221YL□-□□□	220±25%	0.30	200
MU1608301YL□-□□□	300±25%	0.35	150
MZ1608601YL□-□□□	600±25%	0.45	100
MZ1608102YL□-□□□	1000±25%	0.60	100
MG1608152YL□-□□□	1500±25%	0.70	50
MG1608202YL□-□□□	2000±25%	0.80	50

- 1). □ : Packaging Information... [A] : Bulk [B] : Taping Reel
 2). "- □□□□": Reference code



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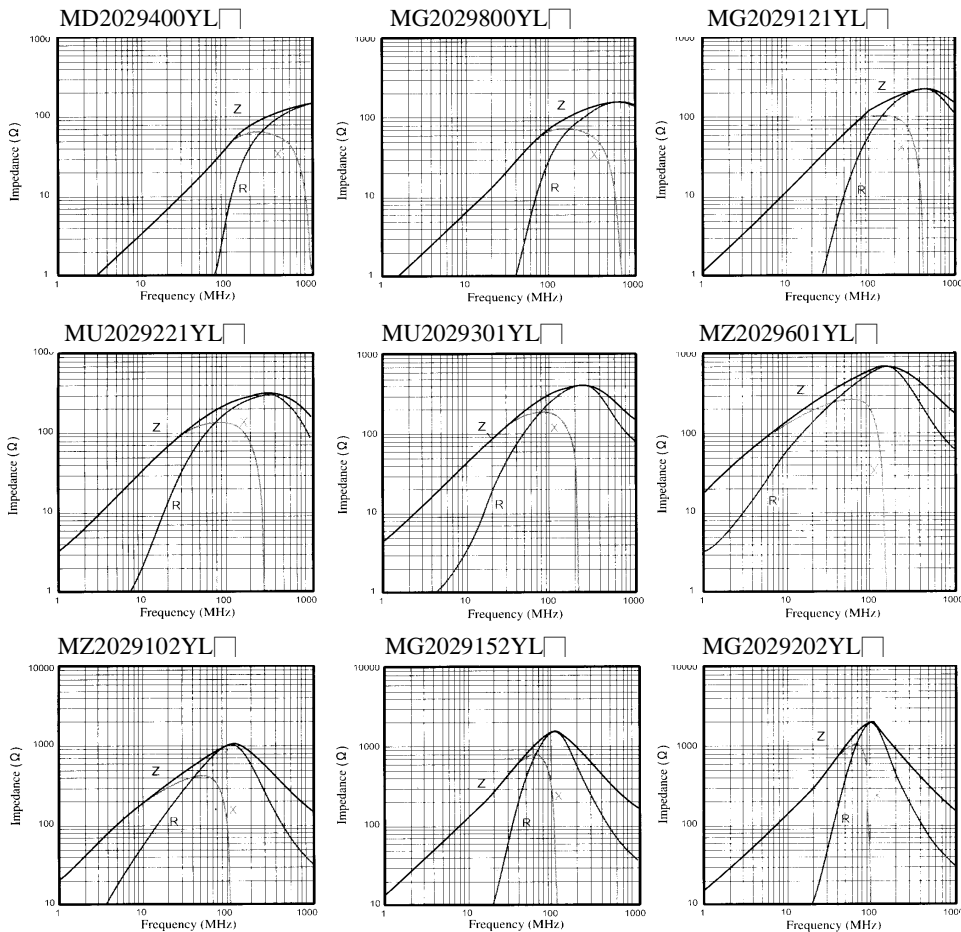
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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	M□□□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

V . ELECTRICAL CHARACTERISITCS :

DWG No.	Impedance (Ω) at 100MHz	RDC (Ω) max.	IDC (mA) max.
MD2029400YL□ -□□□	40±25%	0.20	300
MG2029800YL□ -□□□	80±25%	0.20	300
MG2029121YL□ -□□□	120±25%	0.25	300
MU2029221YL□ -□□□	220±25%	0.30	200
MU2029301YL□ -□□□	300±25%	0.30	200
MZ2029601YL□ -□□□	600±25%	0.40	100
MZ2029102YL□ -□□□	1000±25%	0.45	100
MG2029152YL□ -□□□	1500±25%	0.55	100
MG2029202YL□ -□□□	2000±25%	0.60	50

- 1). □ : Packaging Information... [A]: Bulk [B]: Taping Reel
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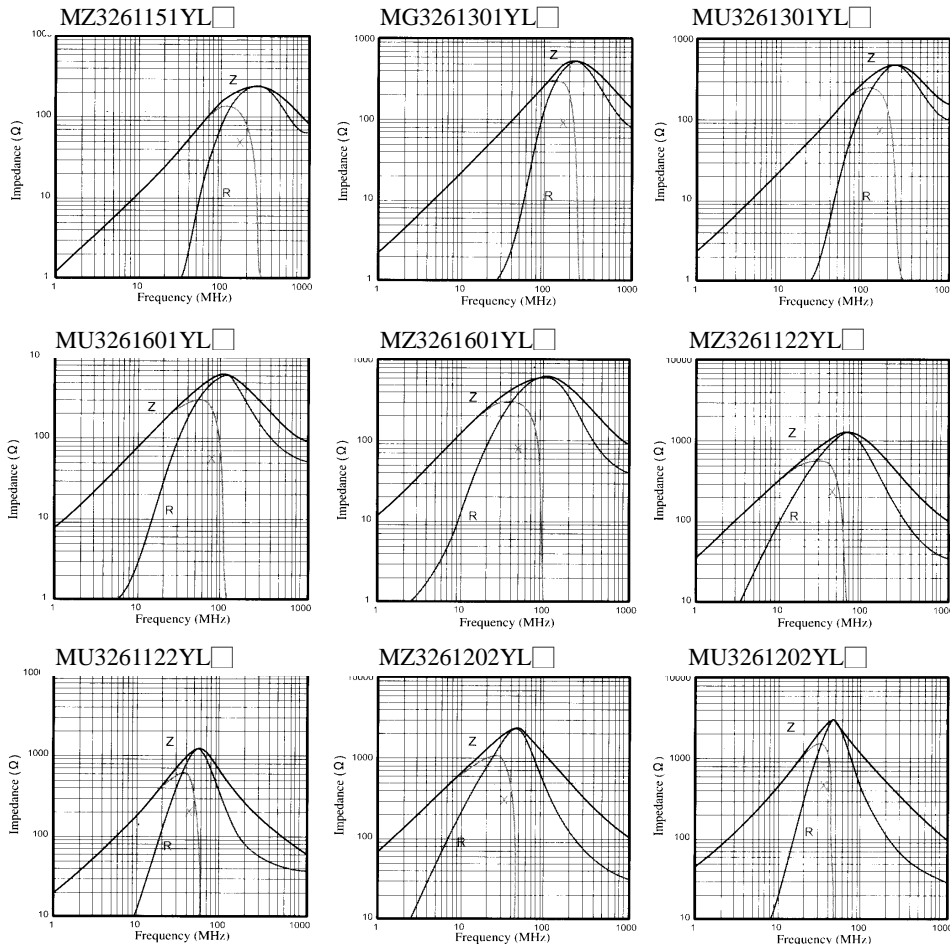
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		ABC'S ITEM NO.	

V . ELECTRICAL CHARACTERISITCS :

DWG No.	Impedance (Ω) at 100MHz	RDC (Ω) max.	IDC (mA) max.
MG3261151YL□-□□□	150±25%	0.30	300
MG3261301YL□-□□□	300±25%	0.30	300
MU3261301YL□-□□□	300±25%	0.30	300
MU3261601YL□-□□□	600±25%	0.30	200
MZ3261601YL□-□□□	600±25%	0.30	200
MZ3261122YL□-□□□	1200±25% (at 50MHz)	0.50	100
MU3261122YL□-□□□	1200±25% (at 50MHz)	0.50	100
MZ3261202YL□-□□□	2000±25% (at 30MHz)	0.60	100
MU3261202YL□-□□□	2000±25% (at 30MHz)	0.60	100

- 1). □ : Packaging Information... [A]: Bulk [B]: Taping Reel
 2). "- □□□":Reference code



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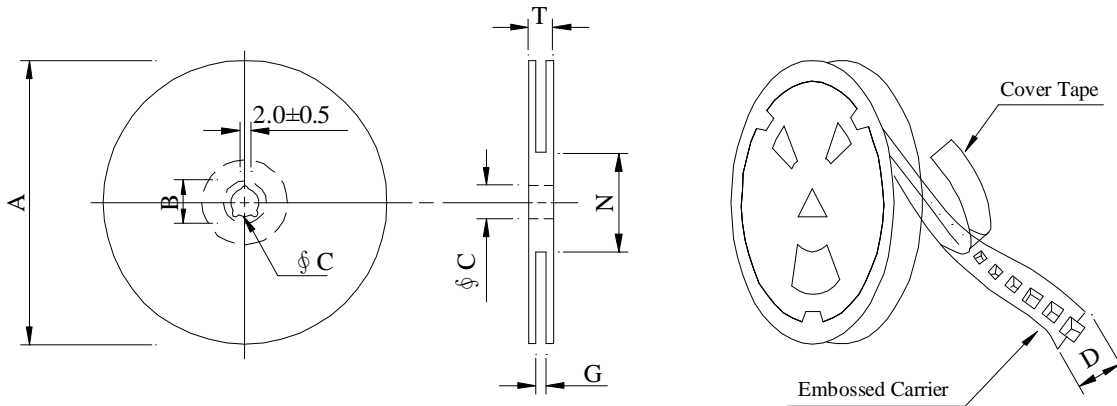
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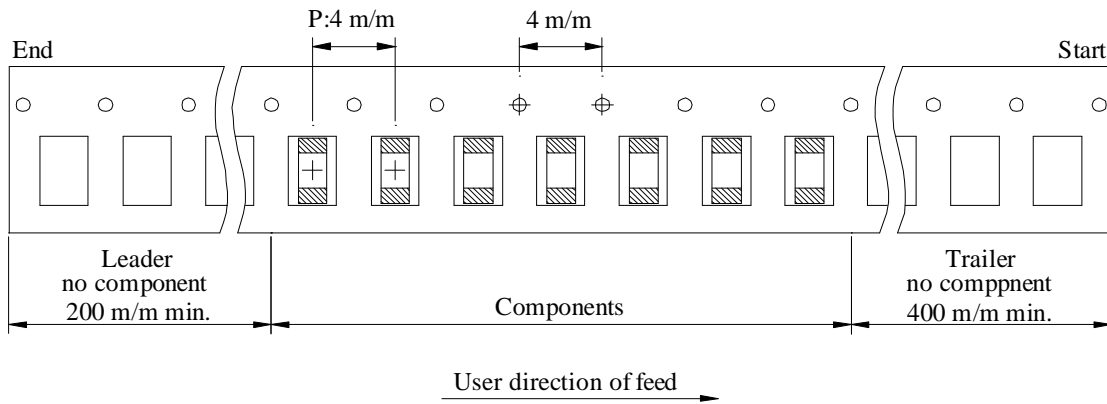
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VI . PACKAGING INFORMATION :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(kpcs)	G.W. (Kg)	Size (cm)
M□1608	4,000	90	07 - 08	200	7.0	41 x 39 x 22
M□2029	4,000	120	07 - 08	200	8.5	41 x 39 x 22
M□3261	3,000	150	07 - 08	120	8.5	41 x 39 x 22

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		ABC'S ITEM NO.	

(4) TYPE DIMENSIONS

Fig 1.

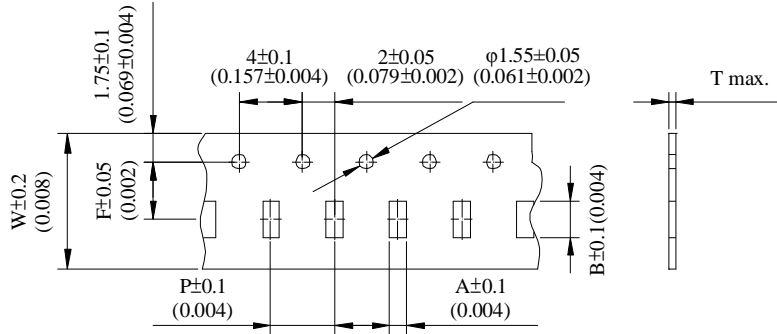
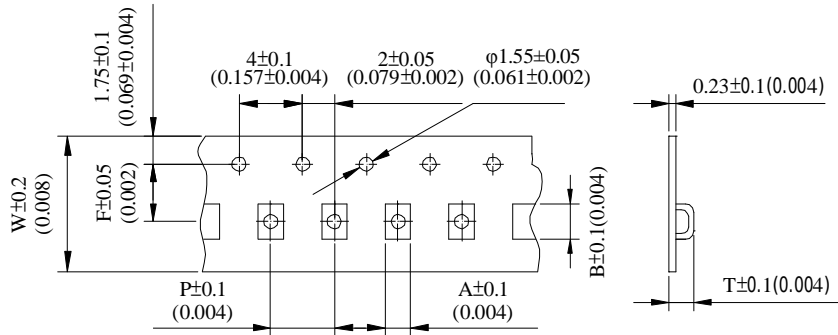


Fig 2.



Unit:m/m

Type	A	B	F	P	T	W	Fig
M□1608	1.05	1.85	3.50	4.0	1.10	8.0	1
M□2029	1.50	2.30	3.50	4.0	1.10	8.0	1
M□3261	1.88	3.50	3.50	4.0	1.27	8.0	2

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